T Normale and	Hits	Search Text	DB	Time stamp
L Number	2	("5,073,456").PN.	USPAT;	2002/03/20 17:05
*	-	(3,0,3,130 , 1111	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
2	2	("6,242,079").PN.	USPAT;	2002/03/20 17:05
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
	0	"metal substrate" and adhesion and	USPAT;	2002/03/07 10:48
_		"interganular etch\$4" and plat\$4 and	US-PGPUB;	2002,00,01 20110
		(immersion or immerse) near6 plating	EPO; JPO;	
		,	DERWENT;	
			IBM TDB	
-	0	"metal substrate" and adhesion and	USPAT;	2002/03/07 10:46
·		"interganular etching" and plat\$4 and	US-PGPUB;	
		(immersion or immerse) near6 plating	EPO; JPO;	
			DERWENT;	
		House I make the House all and adhering and	IBM TDB	2002/03/07 10:47
-	0	"metal substrate" and adhesion and "interganular etch\$4" and plat\$4 and	USPAT; US-PGPUB;	2002/03/07 10:47
		(immersion or immerse) and plating	EPO; JPO;	
		(Induction of Induction) and practing	DERWENT;	
			IBM TDB	
_	0	"metal substrate" and adhesion and	USPAT;	2002/03/07 10:47
		"interganular etch\$4" and plat\$4	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	. 0		USPAT;	2002/03/07 10:48
		"interganular etch\$4"	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	0	"metal substrate" and adhesion and	USPAT;	2002/03/07 10:48
		"intergranular etch\$4" and plat\$4 and	US-PGPUB;	=====================================
		(immersion or immerse) near6 plating	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	"metal substrate" and adhesion and	USPAT;	2002/03/07 10:49
		"intergranular etch\$4" and plat\$4 and	US-PGPUB;	
		(immersion or immerse) and plating	EPO; JPO;	
			DERWENT; IBM TDB	
_	0	"metal substrate" and adhesion and	USPAT;	2002/03/07 10:49
		"intergranular etch\$4" and plat\$4 and	US-PGPUB;	= 302, 00, 0. 10.15
		(immersion or immerse or immers\$4) and	EPO; JPO;	
		plating	DERWENT;	
			IBM TDB	
-	9		USPAT;	2002/03/07 11:14
		intergranular adj1 etch\$4 and plat\$4 and	US-PGPUB;	
		immers\$4	EPO; JPO;	
			DERWENT;	
_	9	metal and adhesion and intergranular adj1	USPAT;	2002/03/07 11:15
		etch\$4 and plat\$4 and immers\$4	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	13		USPAT;	2002/03/07 11:17
		near11 etch\$4 and plat\$4 and immers\$4	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	20	intergrapular and etabéd and mlated and	IBM TDB USPAT;	2002/03/07 11:31
-	28	intergranular and etch\$4 and plat\$4 and immers\$4 and adhesion	US-PGPUB;	2002/03/0/ 11:31
		THURETSY'S AND ADDRESSION	EPO; JPO;	
			DERWENT;	
			IBM TDB	
	l		1	

Page 1

-	0	intergranular and 216.34.ccls	USPAT;	2002/03/07 11:32
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
	0	216.34.ccls	USPAT;	2002/03/07 11:32
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	1	216/34.ccls. and intergranular	USPAT;	2002/03/07 11:32
	_	210/34.ccis. and incorgianatal	US-PGPUB;	2002,00,0. 11.02
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	143	216/34.ccls.	USPAT;	2002/03/07 11:34
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	14	216/34.ccls. and metal and plate and	USPAT;	2002/03/07 11:37
		adhesion	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1	500		IBM TDB	0000/02/07 11-20
-	628	"adhesion promotion" and metal	USPAT;	2002/03/07 11:38
	1		US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	"adhesion promotion" and metal and	USPAT;	2002/03/07 11:38
		intergranualr	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	2002/02/07 11-30
-	2	intergranualr	USPAT; US-PGPUB;	2002/03/07 11:39
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	4381	intergranular	USPAT;	2002/03/07 11:39
			US-PGPUB;	
		,	EPO; JPO;	
			DERWENT; IBM TDB	
_	0	intergranular and "adhesion promotion" and	USPAT;	2002/03/07 11:39
		metal and etch	US-PGPUB;	2002,03,01 11.03
			EPO; JPO;	
1	1		DERWENT;	
	1		IBM TDB	0000 (00 (00)
-	0	=== = j = === == = = = = = = = = = = = = = =	USPAT;	2002/03/07 11:40
	1	and metal and etch	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	3846	inter\$12 and adhes\$12 and promot\$12 and	USPAT;	2002/03/07 11:53
		meta\$12 and etc\$12	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
	005	intentity and adherent and number 12 and	IBM TDB	2002/02/07 11.50
-	205	inter\$12 and adhes\$12 and promot\$12 and meta\$12 and etched	USPAT; US-PGPUB;	2002/03/07 11:56
		metay12 and etched	EPO; JPO;	
			DERWENT;	
	1		IBM TDB	
-	1318017	car andnot vehicle	USPAT;	2002/03/07 11:59
1			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	L		IBM TDB	

				10000/00/00
-	467135	intergranular andnot copper	USPAT;	2002/03/07 12:00
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	2260	interpretary law not connor	IBM TDB USPAT;	2002/03/07 12:00
_	3369	intergranular not copper	US-PGPUB;	2002/03/07 12.00
			EPO; JPO;	
			DERWENT;	·
			IBM TDB	
_	1011	intergranular and copper	USPAT;	2002/03/07 12:00
	1022		US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
	1		IBM TDB	
-	0	intergranular and adhesion near3 promotion	USPAT;	2002/03/07 12:09
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1030	1	USPAT;	2002/03/07 12:10
		promotion	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
	0	intergranular near3 etch and promotion	USPAT;	2002/03/07 12:10
_		intergranular hears etch and promotion	US-PGPUB;	2002/03/07 12:10
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	intergranular near3 etch and adhere	USPAT;	2002/03/07 12:11
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	İ		IBM TDB	
-	6	intergranular and etch and adhere	USPAT;	2002/03/07 13:13
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	118	"copper strike" and nickel and (iron	IBM TDB USPAT;	2002/03/07 13:16
	110	ferrous ferric)	US-PGPUB;	2002/03/07 13:10
		Tollous lolles,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	89	intergranular and etch\$4 and plat\$4 and	USPAT;	2002/03/07 13:19
		immers\$4	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_		IBM TDB	0000 400 405 5 5 5
-	7		USPAT;	2002/03/07 14:15
		immers\$4 and polymer	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	0	("surface grain boundry" intergranular)	IBM TDB USPAT;	2002/03/07 14:18
_		and plate and etch and (copper nickel) and	US-PGPUB;	2002/03/07 14:18
		(immersion immerse) and polymer	EPO; JPO;	
		(Limited State of Alle polymer	DERWENT;	
			IBM TDB	
-	53	("surface grain boundry" intergranular)	USPAT;	2002/03/07 15:54
		and plate and etch	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1	"3265526".PN.	USPAT	2002/03/07 14:27
-	1	"3573100". PN.	USPAT	2002/03/07 14:31
-	1	"3632498".PN.	USPAT	2002/03/07 14:31
1 -	1	"3650861".PN.	USPAT	2002/03/07 14:34
1	1 1	"3706600".PN. "3711385".PN.	USPAT USPAT	2002/03/07 15:37
	<u> </u>	3/11303 .FN.	OSPAT	2002/03/07 15:37

				,
-	1	"3778307".PN.	USPAT	2002/03/07 15:38
_	1	"3864163".PN.	USPAT	2002/03/07 15:39
1_	1	"3878083".PN.	USPAT	2002/03/07 15:39
_	1			2002/03/07 15:40
1	ŀ	"3864163".PN.	USPAT	
-	1	"3878083".PN.	USPAT	2002/03/07 15:40
-	1	"3882002".PN.	USPAT	2002/03/07 15:40
_	1	"3948736".PN.	USPAT	2002/03/07 15:41
<u>-</u>	<u>1</u>	"3950240".PN.	USPAT	2002/03/07 15:42
ļ	_			1 2
-	1	"4005003".PN.	USPAT	2002/03/07 15:43
-	1	"4039400".PN.	USPAT	2002/03/07 15:44
-	1	"4068025".PN.	USPAT	2002/03/07 15:46
1 -	1	"4039400".PN.	USPAT	2002/03/07 15:50
-	ī	"4068025".PN.	USPAT	2002/03/07 15:50
1	i .		1	
-	1	"4140813".PN.	USPAT	2002/03/07 15:51
-	1	"4140813".PN.	USPAT	2002/03/07 15:52
-	1	"4255247".PN.	USPAT	2002/03/07 15:53
<u>-</u>	1	"4272354".PN.	USPAT	2002/03/07 15:53
_	1	"4328080".PN.	USPAT	2002/03/07 15:53
[1			
-	1	"4331528".PN.	USPAT	2002/03/07 15:53
_	1	"4331528".PN.	USPAT	2002/03/07 15:54
_	35	("surface grain boundry" intergranular)	USPAT;	2002/03/12 11:48
		and plate and etch and substrate	US-PGPUB;	
		and prace and econ and substrace		
1			EPO; JPO;	
1			DERWENT;	
			IBM TDB	
-	3	("5205473").PN.	USPAT;	2002/03/08 11:59
	1		US-PGPUB;	=====, ==, == =====
			-	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1	"5092485".PN.	USPAT	2002/03/08 08:39
	_			1
-	48	5205473.uref.	USPAT;	2002/03/08 08:38
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
		H5005450H		0000 (00 (00 00 00
-	50	"5205473"	USPAT	2002/03/08 08:39
-	48	5205473.uref.	USPAT	2002/03/08 08:39
_	1 0	"99/40764"	USPAT;	2002/03/08 12:27
			US-PGPUB;	
			· · · · · · ·	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	8	sadey	USPAT;	2002/03/08 12:35
	1		US-PGPUB;	,,
			EPO; JPO;	
			DERWENT;	
1	1		IBM TDB	
-	11	"5869130"	USPAT;	2002/03/08 12:52
	1		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1		IBM TDB	
-	54522	pcb intergranular	USPAT;	2002/03/08 12:52
			US-PGPUB;	=
1			EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
l _	10	pcb and intergranular	USPAT;	2002/03/08 12:56
	1			2002,00,00 12.00
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
]		IBM TDB	
_	368	(adhere adhesion) and intergranular	USPAT;	2002/03/08 12:56
	306	(adhere adhesion) and intergranular	· ·	2002/03/00 12:36
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	l i
1			IBM TDB	
1	l		TD11 1 DD	

	18	(adhere adhesion) and intergranular and	USPAT;	2002/03/08 13:04
		etch and (organic polymer)	US-PGPUB;	
		Coon and (organize porymor)	EPO; JPO;	
			1	
			DERWENT;	
			IBM TDB	
-	500244	(adhere adhesion) mear promotion	USPAT;	2002/03/08 13:05
1		(intergranular "grain boundary") and etch	US-PGPUB;	
1		and (organic polymer)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
	1,172	/	1	2002/03/08 13:05
_	1173	(adhere adhesion) near promotion	USPAT;	2002/03/08 13.03
		(intergranular "grain boundary") and etch	US-PGPUB;	
		and (organic polymer)	EPO; JPO;	
	l		DERWENT;	
			IBM TDB	
l _	1173	(adhere adhesion) near1 promotion	USPAT;	2002/03/08 13:05
	11/3	(intergranular "grain boundary") and etch	US-PGPUB;	2002,00,00 13.00
			· ·	
		and (organic polymer)	EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
_	933	(adhere adhesion) near1 promotion	USPAT;	2002/03/08 13:06
		(intergranular "grain boundary") near1	US-PGPUB;	
1		etch and (organic polymer)	EPO; JPO;	
		econ and (organic porymer)		
			DERWENT;	
	<u> </u>		IBM TDB	
-	923	(adhere adhesion) near1 promotion	USPAT;	2002/03/08 13:06
		(intergranular "grain boundary") near1	US-PGPUB;	1
		etch and (organic polymer) and circuit	EPO; JPO;	
			DERWENT;	
			,	
	000		IBM TDB	0000 (00 (00 10 06
_	923	(adhere adhesion) near1 promotion	USPAT;	2002/03/08 13:06
		(intergranular "grain boundary") near1	US-PGPUB;	
		etch and (organic polymer) and circuit	EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
	0	(adhere adhesion) near1 promotion near1	USPAT;	2002/03/08 13:07
_	0	(adhere adhesion) heart promotion heart	1	2002/03/00 13:07
		(intergranular "grain boundary") near1	US-PGPUB;	
		etch and (organic polymer) and "circuit	EPO; JPO;	
		board"	DERWENT;	
			IBM TDB	
_	0	(adhere adhesion) near1 promotion and	USPAT;	2002/03/08 13:07
		(intergranular "grain boundary") near1	US-PGPUB;	
		etch and (organic polymer) and "circuit	EPO; JPO;	
			1	
		board"	DERWENT;	
			IBM TDB	
_	2	(adhere adhesion) near1 promotion and	USPAT;	2002/03/08 13:11
		(intergranular "grain boundary")	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
	1		IBM TDB	
l _	0	"(adhere adhesion) near1 promotion".ti.	USPAT;	2002/03/12 11:00
-		(admere admesson) heart promotion .cl.		2002/03/12 11:00
			US-PGPUB;	1
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	58	"adhesion promotion".ti.	USPAT;	2002/03/08 15:11
		and the promote that	US-PGPUB;	=====================================
			I	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1	"3508983".PN.	USPAT	2002/03/08 14:38
-	1	"3698940".PN.	USPAT	2002/03/08 14:38
_	1	"3698940".PN.	USPAT	2002/03/08 14:38
l _	1	"3873499".PN.	USPAT	2002/03/08 14:38
1_	i .			
1 -	1	"3978252".PN.	USPAT	2002/03/08 14:38
-	1	"4042729".PN.	USPAT	2002/03/08 14:38
-	1	"4100312".PN.	USPAT	2002/03/08 14:38
1 -	1	"4159222".PN.	USPAT	2002/03/08 14:38
-	1	"4499152".PN.	USPAT	2002/03/08 14:38
	1	"4574031".PN.	USPAT	2002/03/08 14:38
1_	1		i	2002/03/08 14:38
ı 	1	"4897118".PN.	USPAT	2002/03/00 14:38

	1	"4902556".PN.	USPAT	2002/03/08 14:38
-	1	"4976990".PN.	USPAT	2002/03/08 14:38
-	1	"5061550".PN.	USPAT	2002/03/08 14:38
-	1	"5071701".PN.	USPAT	2002/03/08 14:38
-	1	"5073456".PN.	USPAT	2002/03/08 14:38
-	1	"5153024".PN.	USPAT	2002/03/08 14:38
-	8	"intergranular etch" and adhesion	USPAT;	2002/03/08 15:12
			US-PGPUB;	
			EPO; JPO;	1
			DERWENT;	
			IBM TDB	
	2	"boundary layer" near11 etch and adhesion	USPAT;	2002/03/08 15:33
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	1
			IBM TDB	
-	1		USPAT	2002/03/08 15:14
-	112	metal near polymer near adhesion	USPAT;	2002/03/08 16:12
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	•
			IBM TDB	0000 (00 (00 100 100 100 100 100 100 100
_	1126	427/304.ccls.	USPAT;	2002/03/08 16:13
			US-PGPUB;	1
			EPO; JPO;	1
	1		DERWENT;	
			IBM TDB	0000 (00 (00 10 10 10
-	175	427/304.ccls. and adhesion and polymer	USPAT;	2002/03/08 16:13
			US-PGPUB;	
			EPO; JPO;	1
			DERWENT;	
			IBM TDB	
-	3466	bisphenol and plastic near11 can and coat\$	USPAT;	2002/03/12 09:12
	1		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	334	1 •	USPAT;	2002/03/12 09:24
		and food	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	198		USPAT;	2002/03/12 10:12
		"reinforcing bar" and coat\$ and bridge	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
	-	#5272440# PN	IBM TDB	2002/03/12 00:27
_	1	"5372449".PN.	USPAT	2002/03/12 09:37
-	1	"5175032".PN.	USPAT	2002/03/12 09:37
_	1		USPAT;	2002/03/12 10:15
		"reinforcing bar" and coat\$ and bridge and	US-PGPUB;	
		etch	EPO; JPO;	
			DERWENT;	
	_	intonguouslan nagus atah and adharia-	IBM TDB	2002/02/12 10:41
_	9	intergranular near3 etch and adhesion	USPAT;	2002/03/12 10:41
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_	intonguandan noong otah and adharias and	IBM TDB	2002/02/12 10:42
1-	0	intergranular near3 etch and adhesion AND	USPAT;	2002/03/12 10:43
		PROMOT\$4	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1_	926	(adhere adhesion) nearl promotion	IBM TDB	2002/03/12 11:00
-	926	(adhere adhesion) heart promotion	USPAT;	2002/03/12 11:00
	[US-PGPUB; EPO; JPO;	
			DERWENT;	
			i e	
1	1		IBM TDB	1

-	3	(adhere adhesion) near1 promotion and	USPAT;	2002/03/12 11:06
		"copper strike" and etch	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	1
	5	(adhere adhesion) nearl promotion and	USPAT;	2002/03/12 11:41
-)	"copper strike"	US-PGPUB;	2002/03/12 11:41
		Copper Strike	EPO; JPO;	
)		DERWENT;	
			IBM TDB	
_	0	"09/628036"	USPAT;	2002/03/12 11:41
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	0000/00/10 11 11
-	14	"628036"	USPAT;	2002/03/12 11:41
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	2	("6036758").PN.	USPAT;	2002/03/12 12:14
	-	(0050750 7.111.	US-PGPUB;	2002,00,12 12.11
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	("wo 99/40764").CCLS.	USPAT;	2002/03/12 12:14
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		II 00/40764II	IBM TDB	2002/02/12 12:14
_	0	"wo 99/40764"	USPAT;	2002/03/12 12:14
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	"99/40764"	USPAT;	2002/03/12 12:14
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	17	"40764"	USPAT;	2002/03/12 12:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	0	"40764" and adhesive	IBM TDB USPAT;	2002/03/12 12:15
_		10,01 and admestive	US-PGPUB;	2002/03/12 12.13
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	("wo9940764").PN.	USPAT;	2002/03/12 12:23
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		(#0040764#) 777	IBM TDB	2002/02/12 12:02
-	3	("9940764").PN.	USPAT;	2002/03/12 12:23
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	wo009940764	USPAT;	2002/03/12 12:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	. 1
			IBM TDB	
-	0	wo9940764	USPAT;	2002/03/12 15:00
]		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	L		IBM TDB	L

				10000 (00 (00 00 00 00
1-	0	wo009617975	USPAT; US-PGPUB;	2002/03/12 15:00
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	wo9617975	USPAT;	2002/03/12 15:01
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	0	"wo9617975"	USPAT;	2002/03/12 15:01
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	5	H06170764	IBM TDB	2002/03/12 16:26
-	5	"9617975"	USPAT; US-PGPUB;	2002/03/12 10:26
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
 	8	"9619097"	USPAT;	2002/03/13 12:52
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	1	("copper strike" and adhesion).ti.	USPAT;	2002/03/13 13:02
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	423	("intergranular" or "grain boundary" and	IBM TDB USPAT;	2002/03/13 13:07
-	423	adhesion).ti.	US-PGPUB;	2002/03/13 13:07
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	2	, , ,	USPAT;	2002/03/13 13:10
		boundary") and adhesion).ti.	US-PGPUB; EPO; JPO;	'
			DERWENT;	
			IBM TDB	
-	1	JP03130142A	USPAT;	2002/03/13 13:12
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	2	("grain boundary" or intergranular) and	USPAT;	2002/03/13 13:15
		adhesion near5 promotion	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	1231	("grain boundary" or intergranular) and	IBM TDB USPAT;	2002/03/13 13:16
	1231	adhesion	US-PGPUB;	2002,00,10
			EPO; JPO;	
			DERWENT;	
			IBM TDB	0000/00/10 11 11
-	13	1 ' 2 ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '	USPAT;	2002/03/13 14:34
		etch and adhesion	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1	"4797182".PN.	USPAT	2002/03/13 13:22
-	19	1 , 2	USPAT;	2002/03/13 15:27
ļ		surface roughening) near5 etch near5	US-PGPUB;	
		plating and adhesion near5 (enhanced enhance enhances enhancing improve	EPO; JPO; DERWENT;	
		improves improving improved)	IBM TDB	
_	1		USPAT	2002/03/13 15:08
		·	·	

- 2150 428/209.ccls.		····			1 0000 (00 (10 0 10 0 0 0 0 0 0 0 0 0 0
- 1035949 428/209.ccls. and (etch etched roughen "grain boundary" intergranular) and (adnere adhesion) (copper nickel tin silver bismuth gold cadmium) and (adhere adhesion) and (copper nickel tin silver bismuth gold cadmium) (adhere adhesion) and (copper nickel tin silver bismuth gold cadmium) (proper nickel tin silver) (proper nickel tin silver bismuth gold cadmium) (proper nickel tin silver) (p	_	2150	428/209.ccls.	USPAT;	2002/03/13 15:29
- 33				1	
IBM TOB US-RCPUB; US-RCP				· ·	
Size					
"grain boundary" intergranular) and (adhere adhesion) US-RCPUB; EPO; JFO; DERMENT; US-RCPUB; USPAT;	_	337	428/209.ccls. and (etch etched roughen		2002/03/13 15:31
Cadhere adhesion					
-					
1035949					
"grain boundary" intergranular) and (adhere adhesion) (copper nickel tin silver bismuth gold cadmium) - 310 428/209.ccls. and (etch etched roughen "grain boundary" intergranular) and (adhere adhesion) and (copper nickel tin silver bismuth gold cadmium) - 251 428/209.ccls. and (etch etched roughen "grain boundary" intergranular) and (adhere adhesion) and (copper nickel tin silver bismuth gold cadmium) and metal and (adhere adhesion) and (copper nickel tin silver bismuth gold cadmium) and metal and substrate ("5800859").PN. - 3 ("3,650,861").PN. - 3 ("3,773,577").PN. - 5 ("3,773,577").PN. - 2 ("6162503").PN. - 2 ("6162503").PN. - 2 ("5,869,130").PN. - 3 4 etch and plate and (electroless electroplate "immersion plate") and "hydrogen peroxide" near10 (sulfonic SO3H) - 4 etch and plate and (electroless electroplate "immersion plate") and "hydrogen peroxide" near10 (sulfonic SO3H) - 689 thiazcle and "hydrogen peroxide" near10 acid "bydrogen peroxide" near10 acid "bydro				IBM TDB	
(addnere adhesion) (copper nickel tin silver bismuth gold cadmium)	_	1035949		USPAT;	2002/03/13 15:33
Silver bismuth gold cadmium DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; JPO; DERMENT; IBM TOB USPAT; USPGUB; EPO; JPO; JPO; JPO; JPO; JPO; JPO; JPO; J			"grain boundary" intergranular) and	US-PGPUB;	
310 428/209.ccls. and (etch etched roughen "grain boundary" intergranular) and (adhere adhesion) and (copper nickel tin silver bismuth gold cadmium) and (adhere adhesion) and (copper nickel tin silver bismuth gold cadmium) and (aghere adhesion) and (copper nickel tin silver bismuth gold cadmium) and (aghere adhesion) and (copper nickel tin substrate ("5800859").PN. - 3 ("3,650,861").PN. - 3 ("3,650,861").PN. - 5 ("3,773,577").PN. - 5 ("3,773,577").PN. - 7 2 ("6162503").PN. - 8 2 ("6162503").PN. - 9 2 ("5,869,130").PN. - 1 1 surfeel ("5,869,130").PN. - 1 2 ("5,869,130").PN. - 1 2 ("5,869,130").PN. - 1 2 ("5,869,130").PN. - 1 34 etch and plate and (electroless electroplate "immersion plate") and "hydrogen peroxide" and (sulfonic SO3H) (SPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-P		ŀ			
310 428/209.ccls. and (etch etched roughen grain boundary" intergranular) and (adhere adhesion) and (copper nickel tin silver bismuth gold cadmium) Copper nickel tin silver bismuth gold cadmium) Copper nickel tin silver bismuth gold cadmium) Copper nickel tin silver bismuth gold cadmium) and metal and substrate Copper nickel tin silver bismuth gold cadmium) and metal and substrate Copper nickel tin silver bismuth gold cadmium) and metal and substrate Copper nickel tin silver bismuth gold cadmium) and metal and substrate Copper nickel tin silver bismuth gold cadmium) and metal and substrate Copper nickel tin silver bismuth gold cadmium) and metal and substrate Copper nickel tin silver bismuth gold cadmium) Copper nickel tin silver bismuth gold cadmium) Copper nickel tin silver bismuth gold cadmium Copper silver Copper sil			silver bismuth gold cadmium)		
"grain boundary" intergranular) and (achere achesion) and (copper nickel tin silver bismuth gold cadmium) 1287, 2002 1287, 2002 1287, 2002 1287, 2002 1287, 2002 1287, 2002 1287, 2002 1287, 2002 1287, 2002 1287, 2002 1287, 2002 2				;	0000 (00 (10 15 00)
(adhere adhesion) and (copper nickel tin silver bismuth gold cadmium) SEPO; JPO; DERWENT; IBM TDB USPAT; US-PCPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-	-	310		1	2002/03/13 15:33
Silver bismuth gold cadmium DERWENT; IBM TDB USPAT; US-PGFUB; EPO; JPO; JPO; DERWENT; IBM TDB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGFUB; EPO; JPO; JPO; DERWENT; US-PGFUB; EPO; J			"grain boundary" intergranular) and	1	
251 428/209.ccls. and (etch etched roughen "grain boundary" intergranular) and (adhere adhesion) and (copper nickel tin silver bismuth gold cadmium) and metal and substrate ("5800859").PN. Ph.					
251 428/209.ccls. and (etch etched roughen grain boundary" intergranular) and (adhere adhesion) and (copper nickel tin silver bismuth gold cadmium) and metal and substrate ("5800859").PN.			sliver bismuth gold cadmium)		
"grain boundary" intergranular) and (adhere adhesion) and (copper nickel tin silver bismuth gold cadmium) and metal and substrate ("5800859").PN. PN.	_	251	120/200 gala and (atah atahod royahan		2002/03/16 10:50
Cathere adhesion) and (copper nickel tin silver bismuth gold cadmium) and metal and substrate ("5800859").PN. Copper	_	231		•	2002/03/10 10.30
Silver bismuth gold cadmium) and metal and substrate ("5800859").PN. DERWENT; IBM TOB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TOB USPAT; USPAT			(adhere adhesion) and (conner nickel tin	1	
Substrate					
3					
- 33 ("3,650,861").PN. USPAT; IBM TDB USPAT; ISM TD	_	3			2002/03/16 11:36
- 3 ("3,650,861").PN.			,	1	
- 3 ("3,650,861").PN.				•	
- 3 ("3,650,861").PN. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB					
- 5 ("3,773,577").PN. - 5 ("3,773,577").PN. - 2 ("6162503").PN. - 2 ("6162503").PN. - 2 ("5,869,130").PN. - 3 4 etch and plate and (electroless electroplate "immersion plate") and "hydrogen peroxide" near10 acid "hydrogen peroxide" near10 acid "hydrogen peroxide" near10 acid "bydrogen peroxide" near10 acid "bydr				IBM TDB	
- 5 ("3,773,577").PN. - 5 ("3,773,577").PN. - 2 ("6162503").PN. - 2 ("5,869,130").PN. - 2 ("5,869,130").PN. - 34 etch and plate and (electroless electroplate "immersion plate") and "hydrogen peroxide" near10 acid "byArr; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US	-	3	("3,650,861").PN.	USPAT;	2002/03/16 12:13
- 5 ("3,773,577").PN. - 2 ("6162503").PN. - 2 ("6162503").PN. - 2 ("5,869,130").PN. - 3 4 etch and plate and (electroless electroplate "immersion plate") and "hydrogen peroxide" near10 acid "hydrogen peroxide" near10 acid "byPAT; USPAT; USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EP					
TBM TDB					
- 5 ("3,773,577").PN. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; D				· ·	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO;		_	480 550 5558	l.	0000/00/15 10 10
- 2 ("6162503").PN.	_	5	("3,773,577").PN.		2002/03/16 13:19
- 2 ("6162503").PN. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT; USPAGPUB; EPO; JPO; DERWENT; USPAGPUB; USPAGPUB; USPAGPUB; USPAGPUB; USPAGPUB; USPAGPUB; USPAGPUB;					
TBM TDB					
- 2 ("6162503").PN. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB US					
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DE	_	2	("6162503") PN		2002/03/16 13:22
EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;		2	(0102303):111.		2002/03/10 13.22
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;				•	
- 2 ("5,869,130").PN. IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EFO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT			-		
- 2 ("5,869,130").PN. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EFO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EFO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EFO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; ISM TDB USPAT; US-PGPU					
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	_	2	("5,869,130").PN.		2002/03/16 15:51
- 1 surfeel EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO;					
- 1 surfeel Surfeel USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT					
- 1 surfeel USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;				DERWENT;	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; electroplate "immersion plate") and "hydrogen peroxide" and (sulfonic SO3H) etch and plate and (electroless electroplate "immersion plate") and "hydrogen peroxide" near10 (sulfonic SO3H) EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;	,			!	
EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; electroplate "immersion plate") and etch and plate and (electroless electroplate and (sulfonic SO3H) EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; electroplate "immersion plate") and "hydrogen peroxide" near10 (sulfonic SO3H) EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; acid US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT;	_	1	surfeel		2002/03/16 16:02
- 34 etch and plate and (electroless electroplate "immersion plate") and US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; Electroplate "immersion plate") and "hydrogen peroxide" near10 (sulfonic SO3H) EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; DERWENT; DERWENT; EPO; JPO; DERWENT;					
etch and plate and (electroless electroplate "immersion plate") and "hydrogen peroxide" and (sulfonic SO3H) etch and plate and (sulfonic SO3H) etch and plate and (electroless electroplate "immersion plate") and "hydrogen peroxide" near10 (sulfonic SO3H) thiazole and "hydrogen peroxide" near10 acid iBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;					
- 34 etch and plate and (electroless electroplate "immersion plate") and "hydrogen peroxide" and (sulfonic SO3H) - 1 etch and plate and (electroless electroplate "immersion plate") and "hydrogen peroxide" near10 (sulfonic SO3H) - 689 thiazole and "hydrogen peroxide" near10 acid					
electroplate "immersion plate") and "hydrogen peroxide" and (sulfonic SO3H) 1 etch and plate and (electroless electroplate "immersion plate") and "hydrogen peroxide" near10 (sulfonic SO3H) This is a substituted by the state of the state	_	24	otch and plate and /olostroloss	[2002/02/16 16-11
"hydrogen peroxide" and (sulfonic SO3H) EPO; JPO; DERWENT; IBM TDB USPAT; electroplate "immersion plate") and "hydrogen peroxide" near10 (sulfonic SO3H) thiazole and "hydrogen peroxide" near10 acid "hydrogen peroxide" and "sulfonic SO3H) EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT;	_	34		I .	2002/03/10 10:11
DERWENT; IBM TDB USPAT; electroplate "immersion plate") and "hydrogen peroxide" near10 (sulfonic SO3H) thiazole and "hydrogen peroxide" near10 acid DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT;					
thiazole and "hydrogen peroxide" near10 (sulfonic SO3H) thiazole and "hydrogen peroxide" near10 (sulfonic SO3H) thiazole and "hydrogen peroxide" near10 uspat; acid acid IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;			mydrogen peroxide and (suffonic sosh)	1	
etch and plate and (electroless electroplate "immersion plate") and "hydrogen peroxide" near10 (sulfonic SO3H) thiazole and "hydrogen peroxide" near10 uspat; acid thiazole and "hydrogen peroxide" near10 uspat;				1	
electroplate "immersion plate") and "hydrogen peroxide" near10 (sulfonic SO3H) thiazole and "hydrogen peroxide" near10 US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; DERWENT;	·_	1	etch and plate and (electroless	1	2002/03/18 09:59
"hydrogen peroxide" near10 (sulfonic SO3H) EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; Output DERWENT; DERWENT;		•			====, ==, == = = = = = = = = = = = = =
- 689 thiazole and "hydrogen peroxide" near10 uspat; acid USPAT; US-PGPUB; EPO; JPO; DERWENT;					
thiazole and "hydrogen peroxide" near10 USPAT; US-PGPUB; EPO; JPO; DERWENT;			, , , , , , , , , , , , , , , , , , , ,	1	
acid US-PGPUB; EPO; JPO; DERWENT;				!	
acid US-PGPUB; EPO; JPO; DERWENT;	-	689	thiazole and "hydrogen peroxide" near10	!	2002/03/18 10:01
DERWENT;					
				EPO; JPO;	
IBM TDB				DERWENT;	
				IBM TDB	

-	3	thiazole and "hydrogen peroxide" near10	USPAT;	2002/03/18 10:02
		acid and "printed circuit board"	US-PGPUB;	
		<u>-</u>	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	3366	"aspect ratio" near3 "5"	USPAT;	2002/03/19 09:06
	5555	dopodo zuemo menero	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	445	# 2 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	IBM TDB	2002/03/19 09:07
-	117	"aspect ratio" near3 "5" and etch	USPAT;	2002/03/19 09:07
			US-PGPUB;	
			EPO; JPO;	ļ
			DERWENT;	
			IBM TDB	
-	3	,	USPAT;	2002/03/19 09:10
		grain and boundary	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		•	IBM TDB	
_	0	"aspect ratio\$2" near3 "5" and etch and	USPAT;	2002/03/19 09:11
	-	(grain or boundary)	US-PGPUB;	
		, , , , , , , , , , , , , , , , , , ,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
1_	33	aspect near2 ratio\$2 near3 "5" and etch	USPAT;	2002/03/19 09:15
	55	and (grain or boundary)	US-PGPUB;	
		and (grain or boundary)	EPO; JPO;	
1				
1			DERWENT;	
			IBM TDB	0000/00/10 00 15
-	0	aspect near2 ratio\$2 near3 etch near22	USPAT;	2002/03/19 09:15
		(grain or boundary)	US-PGPUB;	
1			EPO; JPO;	
1			DERWENT;	
1			IBM TDB	
-	53	aspect near2 ratio\$2 near3 etch and (grain	USPAT;	2002/03/19 11:29
		or boundary)	US-PGPUB;	
		-	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	3	"40764" and phenyl	USPAT;	2002/03/19 11:31
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	("wo9940764").PN.	USPAT;	2002/03/19 11:31
	J	(1100010101 / 111111	US-PGPUB;	-002, 00, 10 11.01
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	3	("QQ40764") DN	t .	2002/03/19 11:34
-	3	("9940764").PN.	USPAT;	2002/03/19 11:34
			US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
			IBM TDB	0000/05/55 55 5
-	2	GRIESER.in. and HAUF.in.	USPAT;	2002/03/19 11:35
1			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	3	GRIESER.in. and copper	USPAT;	2002/03/19 11:35
	-	^	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	209	GRIESER.in.	USPAT;	2002/03/19 12:44
	209	OKTEODIK, III.	US-PGPUB;	=====================================
			EPO; JPO;	
			DERWENT;	
			IBM TDB	

	1	COTTOOD	TIODAM.	2002/02/10 12-16
-	3	GRIESER.in. and copper	USPAT; US-PGPUB;	2002/03/19 12:16
	ļ		EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	4	GRIESER.in. and meyer.in.	USPAT;	2002/03/19 12:17
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	10	"9900243"	USPAT;	2002/03/19 12:44
		3300210	US-PGPUB;	2002,00,25
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	"de9900243"	USPAT;	2002/03/19 12:44
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	0	"de99/00243"	USPAT;	2002/03/19 12:44
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		(##) 00 (000 40 ##) ======	IBM TDB	0000/00/10 10 15
-	0	(""de99/00243"").CCLS.	USPAT;	2002/03/19 12:45
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	(""99/00243"").CCLS.	USPAT;	2002/03/19 12:47
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		Nic mot identical to the cultimic colonia	IBM TDB	2002/02/10 12-40
-	0	"is not identical to the sulfinic, selenic or tellurinic"	USPAT; US-PGPUB;	2002/03/19 12:49
		or certarinic	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	"seleninic or tellurinic"	USPAT;	2002/03/19 13:03
			US-PGPUB;	
	}		EPO; JPO;	
			DERWENT;	
_	55	"seleninic"	IBM TDB USPAT;	2002/03/19 12:57
1	33	5010111110	US-PGPUB;	2002,00,10 12.07
1			EPO; JPO;	
}			DERWENT;	
			IBM TDB	
-	0	("wo9940764").PN.	USPAT;	2002/03/19 12:58
			US-PGPUB;	
1			EPO; JPO; DERWENT;	
			IBM TDB	
_	o	("WO9940764").PN.	USPAT;	2002/03/19 12:58
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		220000010761	IBM TDB	0000/00/10 10 ==
-	0	WO009940764	USPAT;	2002/03/19 12:58
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	3	"9940764"	USPAT;	2002/03/19 12:59
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	

		1-1-1-1-1	LICDAM.	2002/03/19 13:25
-	0	seleninic near3 tellurinic	USPAT; US-PGPUB;	2002/03/19 13:25
			EPO; JPO;	
			DERWENT;	
			IBM TDB	2002/02/10 12:05
-	2144	formamidine	USPAT; US-PGPUB;	2002/03/19 13:25
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	323	"formamidine sulfinic acid"	USPAT;	2002/03/19 13:26
		,	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	104	"formamidine sulfinic acid" and copper	USPAT;	2002/03/19 13:26
	1		US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	1	"formamidine sulfinic acid" and copper and	USPAT;	2002/03/19 14:34
	_	etch	US-PGPUB;	2002,00,25 21101
	· ·		EPO; JPO;	
			DERWENT;	
	3	(#4002202#) PM	IBM TDB	2002/03/19 15:08
_	3	("4882202").PN.	USPAT; US-PGPUB;	2002/03/19 13:08
			EPO; JPO;	
·			DERWENT;	
	_		IBM TDB	
_	0	("surface.ti. rough\$5.ti.").PN.	USPAT;	2002/03/19 15:10
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	652210	surface.ti. rough\$5.ti.	USPAT;	2002/03/19 15:10
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	63	selenic and telluric	USPAT;	2002/03/19 15:11
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	0	"selenic or telluric"	USPAT;	2002/03/19 15:21
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
-	0	"selenic near3 telluric"	USPAT;	2002/03/19 15:21
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	o	"selenic near4 telluric"	USPAT;	2002/03/19 15:21
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	0	"selenic near telluric"	IBM TDB USPAT;	2002/03/19 15:22
		Societio mode containe	US-PGPUB;	1002,03,13 10.22
			EPO; JPO;	
			DERWENT;	
	0	 "selenic adj3 telluric"	IBM TDB USPAT;	2002/03/19 15:23
-		serenic adla cerratio	US-PGPUB;	2002/03/19 13:23
			EPO; JPO;	
			DERWENT;	
			IBM TDB	

US-PGPUB; EPO, JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO, JPO;	<u>-</u>	0	"selenic near45 telluric"	USPAT;	2002/03/19 15:23
Pep	-	0	Selenic hear4) terruric		2002/03/13 13.23
IBM TDB					
- 0 selenic near4 telluric. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;				1	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB 2002/03/19 15: US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; USPAT; US-PGPUB;		_	salania maana tallumia		2002/03/19 15.22
PPC, JPC, DERMENT; IBM TDB 2002/03/19 15: US-PGPUB; EPC, JPC; DERMENT; IBM TDB 2002/03/19 15: US	-	"	Selenic hear4 telluric.		2002/03/19 13:23
TEM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IEM TDB USPAT;				1	
- 0 selenic near3 telluric. USPAT; US-PGPUB; EPO; JPO; DERWENT; IEM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;				1	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO;		_		l .	
CEPC; JPC; DERWENT; IBM TDB CO02/03/19 15: CEPC; JPC; DERWENT; IBM TDB CEPC; JPC; JPC; DERWENT; IBM TDB CEPC; JPC; DERWENT; IBM TDB CEPC; JPC; JPC; DERWENT; IBM TDB CEPC; JPC; DERWENT; IBM TDB CEPC; JPC; JPC; DERWENT; IBM TDB CEPC; JPC; JPC; DERWEN	-	0	selenic near3 telluric.	·	2002/03/19 15:24
DERMENT; IBM TDB USPAT; US-PGPUB; EPO, JPO; DERWENT; IBM TDB					
- 0 selenic near2 telluric. Selenic near2 telluric. USPAT; US-PGPUB; EPO; JPO; DERWENT; IEM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO				1	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; USPAT; US-PGPUB; USPAT; USPAT; USPAT;				IBM TDB	
Company Comp		0	selenic near2 telluric.		2002/03/19 15:24
DERWENT; IBM TDB USPAT; US-PGPUB; EP0; JP0; DERWENT; US-PGPUB; EP0; JP0; DERWENT; US-PGPUB; EP0; JP0; DERWENT; US-PGPUB; EP0; JP0; DERWENT; US-PGPUB; EP0; J					
IBM TDB					
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB					
EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	-	0	selenic near1 telluric.	USPAT;	2002/03/19 15:24
DERWENT; IBM TOB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TOB					
IBM TDB					
- 0 selenic near telluric. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO;					
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; U	_	0	selenic near telluric.		2002/03/19 15:24
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB					
- 0 selenic and telluric. IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB EPO; JPO; DERWENT; EPO; JPO; EPO;			1		
- 0 selenic and telluric. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB					
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	_	_	selenic and telluric	i	2002/03/19 15:27
EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB			Selenic and tellulic.		2002/03/19 13.27
TBM TDB					
- 55 seleninic USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB				DERWENT;	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB					0000/00/10 15 04
EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	-	55	seleninic	1	2002/03/19 15:24
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB					
- 0 seleninic and tellurinic USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB					
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB				IBM TDB	
EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB LEDO; JPO; DERWENT; IBM TDB	-	0	seleninic and tellurinic		2002/03/19 15:25
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB				•	
TBM TDB					
US-PGPUB; EPO; JPO; DERWENT; IBM TDB					
EPO; JPO; DERWENT; IBM TDB	-	12	tellurinic		2002/03/19 15:25
DERWENT; IBM TDB					
IBM TDB					
				1	
	-	63	selenic and telluric	USPAT;	2002/03/19 15:27
US-PGPUB;					
EPO; JPO;					
DERWENT; IBM TDB				f -	
	_	40	selenic near4 telluric	ſ	2002/03/19 15:27
US-PGPUB;				US-PGPUB;	
EPO; JPO;					
DERWENT;					
IBM TDB USPAT; 2002/03/19 15:	_	Я	selenic near1 telluric		2002/03/19 15:34
US-PGPUB;		3		•	1002, 00, 10 10:01
EPO; JPO;				EPO; JPO;	
DERWENT;					
	_	207	"copper strike"		2002/02/10 15.25
- 297 "copper strike" USPAT; 2002/03/19 15:	-	291	cobbet active		2002/03/19 15:35
EPO; JPO;					
DERWENT;					
IBM TDB				IBM TDB	<u> </u>

- 216 "copper strike" and nickel USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWEN	. 25
EPO; JPO; DERWENT; IBM TOB USPAT; US-PCPUB; EPO; JPO; DERWENT; I	:35
Topper strike and nickel and plate	-
- 175 "copper strike" and nickel and plate USPAT; US-PCPUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PCPUB; EPO; J	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB	. 35
Copper strike near5 nickel and plate EPG; JPG; DERWENT; IBM TDB USPAT; US-PGPUB; EPG; JPG; JPG; JPG; DERWENT; IBM TDB USPAT; US-PGPUB; EPG; JPG; JPG; JPG; JPG; JPG; JPG; JPG; J	. 33
TBM TDB	
- 43 "copper strike" near5 nickel and plate USPAT; US-PGPUB; EPO; JPO; DERWENT; IEM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IE	
US-PCPUB; EPO; JPO; DERWENT; ILM TOB USPAT; US	. 36
Copper strike near5 nickel and DERWENT; IBM TDB USPAT; US-PGPUB; EPG; JPO; DERWENT; US-PGPUB; USPAT; US-PGPU	. 30
TEM TDB USPAT; USPOUR; EPO; JPO; DERWENT; EMD TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; EPO; J	
- 16 "copper strike" near5 nickel and electroplate electroplate electroplate	
electroplate electroplate Seporation	.48
EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; USPGPUB; EPC; JPC; DERWENT	. 10
- 2353362 roughen\$4 and adhere adn plate USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IEM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; D	
- 2353362 roughen\$4 and adhere adn plate 2353362 roughen\$4 and adhere adn plate USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DE	. 49
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	. , ,
- 1976 roughen\$4 and adhere and plate USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; D	
- 1976 roughen\$4 and adhere and plate 1976 roughen\$4 and adhere and plate USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPA	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DE	. 56
EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT	. 50
- 2 ("6,036,758").PN.	
- 2 ("6,036,758").PN. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT; USPAT; USPAT; USPAT;	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT; USPAT;	.08
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; IBM TDB	
- 3 ("5,907,015").PN. IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; IBM TDB USPAT; USP	
- 3 ("5,907,015").PN. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT; USPAT; USPAT; USPAT;	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; DERWENT; EPO; EPO; EPO; EPO; EPO; EPO; EPO; EPO	:11
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT; USPAT; USPAT; USPAT; USPAT; USPAT; USPAT;	
TBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	
- 2 ("5,807,493").PN. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT; USPAT; USPAT; USPAT; USPAT;	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; 2002/03/19 16	:19
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT; USPAT; USPAT; USPAT; USPAT;	
- 2 ("5,733,599").PN. IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; 2002/03/19 16	
- 2 ("5,733,599").PN. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; 2002/03/19 16	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; 2002/03/19 16	:24
DERWENT; IBM TDB USPAT; 2002/03/19 16	
- 3 ("5712047").PN. IBM TDB USPAT; 2002/03/19 16	
- 3 ("5712047").PN. USPAT; 2002/03/19 16	
IIS-PGPIIR:	:41
EPO; JPO; DERWENT;	
IBM TDB	
- 3 ("5,554,211").PN. USPAT; 2002/03/19 16	:56
US-PGPUB;	
EPO; JPO; DERWENT;	
IBM TDB	
- 2 ("5073456").PN. USPAT; 2002/03/19 17	:12
US-PGPUB;	
EPO; JPO; DERWENT;	
IBM TDB	
- 3 ("5017271").PN. USPAT; 2002/03/20 08	:22
US-PGPUB;	
EPO; JPO; DERWENT;	
IBM TDB	

_	3 ("4642161").PN.	USPAT;	2002/03/20 08:22
		US-PGPUB;	
		EPO; JPO;	
		DERWENT;	
		IBM TDB	